

# MAC3030-8

## Triacs

### Silicon Bidirectional Thyristors

Designed primarily for full-wave AC control applications, such as light dimmers, motor controls, heating controls and power supplies; or wherever full-wave silicon gate controlled solid-state devices are needed. Triac type thyristors switch from a blocking to a conducting state for either polarity of applied main terminal voltage with positive or negative gate triggering.

#### Features

- Blocking Voltage to 250 Volts
- All Diffused and Glass Passivated Junctions for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Gate Triggering Guaranteed in Four Modes (Quadrants)
- Pb-Free Packages are Available\*

#### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) ( $T_J = -40$ to $+125^\circ\text{C}$ , Sine Wave 50 to 60 Hz, Gate Open)	$V_{DRM}$ , $V_{RRM}$	250	V
On-State RMS Current ( $T_C = +70^\circ\text{C}$ ) Full Cycle Sine Wave 50 to 60 Hz	$I_{T(RMS)}$	8.0	A
Peak Non-Repetitive Surge Current (One Full Cycle, Sine Wave 60 Hz, $T_C = +25^\circ\text{C}$ ) Preceded and followed by rated current	$I_{TSM}$	80	A
Circuit Fusing Considerations, ( $t = 8.3$ ms)	$I^2t$	26	$\text{A}^2\text{s}$
Peak Gate Power ( $T_C = +70^\circ\text{C}$ , Pulse Width = 10 $\mu\text{s}$ )	$P_{GM}$	20	W
Average Gate Power ( $T_C = +70^\circ\text{C}$ , $t = 8.3$ ms)	$P_{G(AV)}$	0.35	W
Peak Gate Current ( $T_C = +70^\circ\text{C}$ , Pulse Width = 10 $\mu\text{s}$ )	$I_{GM}$	2.0	A
Operating Junction Temperature Range	$T_J$	$-40$ to $+125$	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	$-40$ to $+150$	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1.  $V_{DRM}$  and  $V_{RRM}$  for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

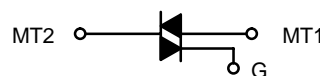
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



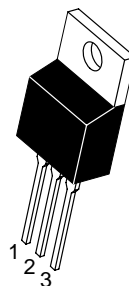
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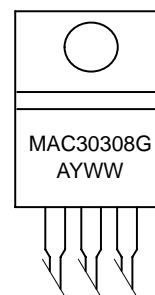
### TRIACS 8.0 AMPERES RMS 250 VOLTS



#### MARKING DIAGRAM



TO-220AB  
CASE 221A-07  
STYLE 4



MAC3030-8 = Standard Device Code  
MAC30308G = Pb-Free Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week

#### PIN ASSIGNMENT

	PIN ASSIGNMENT
1	Main Terminal 1
2	Main Terminal 2
3	Gate
4	Main Terminal 2

#### ORDERING INFORMATION

Device	Package	Shipping
MAC3030-8	TO-220AB	500 Units/Box
MAC3030-8G	TO-220AB (Pb-Free)	500 Units/Box

# MAC3030-8

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case – Junction-to-Ambient	$R_{\theta JC}$ $R_{\theta JA}$	2.0 62.5	$^{\circ}\text{C/W}$
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	$T_L$	260	$^{\circ}\text{C}$

## ELECTRICAL CHARACTERISTICS ( $T_C = 25^{\circ}\text{C}$ unless otherwise noted; Electricals apply in both directions)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Peak Repetitive Blocking Current ( $V_D = \text{Rated } V_{DRM}$ , $V_{RRM}$ ; Gate Open)	$I_{DRM}$ , $I_{RRM}$	– –	– –	10 2.0	$\mu\text{A}$ $\text{mA}$
$T_J = 25^{\circ}\text{C}$ $T_J = +125^{\circ}\text{C}$					

### ON CHARACTERISTICS

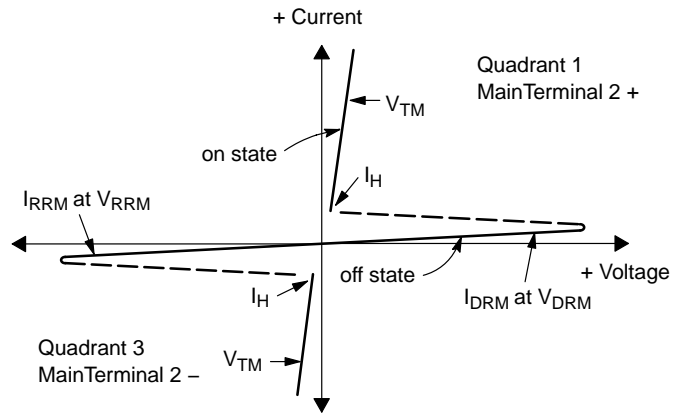
Peak On-State Voltage ( $I_{TM} = \pm 11 \text{ A Peak}$ ; Pulse Width = 1 to 2 ms, Duty Cycle $\leq 2\%$ )	$V_{TM}$	–	1.2	1.65	V
Gate Trigger Current (Continuous dc) (Main Terminal Voltage = 12 Vdc, $R_L = 100 \Omega$ )	$I_{GT}$				$\text{mA}$
MT2(+), G(+)		–	12	50	
MT2(+), G(–)		–	12	50	
MT2(–), G(–)		–	20	50	
MT2(–), G(+)		–	35	75	
Gate Trigger Voltage (Continuous dc) (Main Terminal Voltage = 12 Vdc, $R_L = 100 \Omega$ )	$V_{GT}$				V
MT2(+), G(+)		–	0.9	2.0	
MT2(+), G(–)		–	0.9	2.0	
MT2(–), G(–)		–	1.1	2.0	
MT2(–), G(+)		–	1.4	2.5	
Gate Non-Trigger Voltage (Continuous dc) (Main Terminal Voltage = 12 V, $R_L = 100 \Omega$ , $T_J = +125^{\circ}\text{C}$ ) All Four Quadrants	$V_{GD}$	0.2	–	–	V
Holding Current (Main Terminal Voltage = 12 Vdc, Gate Open, Initiating Current = $\pm 200 \text{ mA}$ , $T_C = +25^{\circ}\text{C}$ )	$I_H$	–	6.0	50	$\text{mA}$
Turn-On Time (Rated $V_{DRM}$ , $I_{TM} = 11 \text{ A}$ ) ( $I_{GT} = 120 \text{ mA}$ , Rise Time = 0.1 $\mu\text{s}$ , Pulse Width = 2 $\mu\text{s}$ )	$t_{gt}$	–	1.5	–	$\mu\text{s}$

### DYNAMIC CHARACTERISTICS

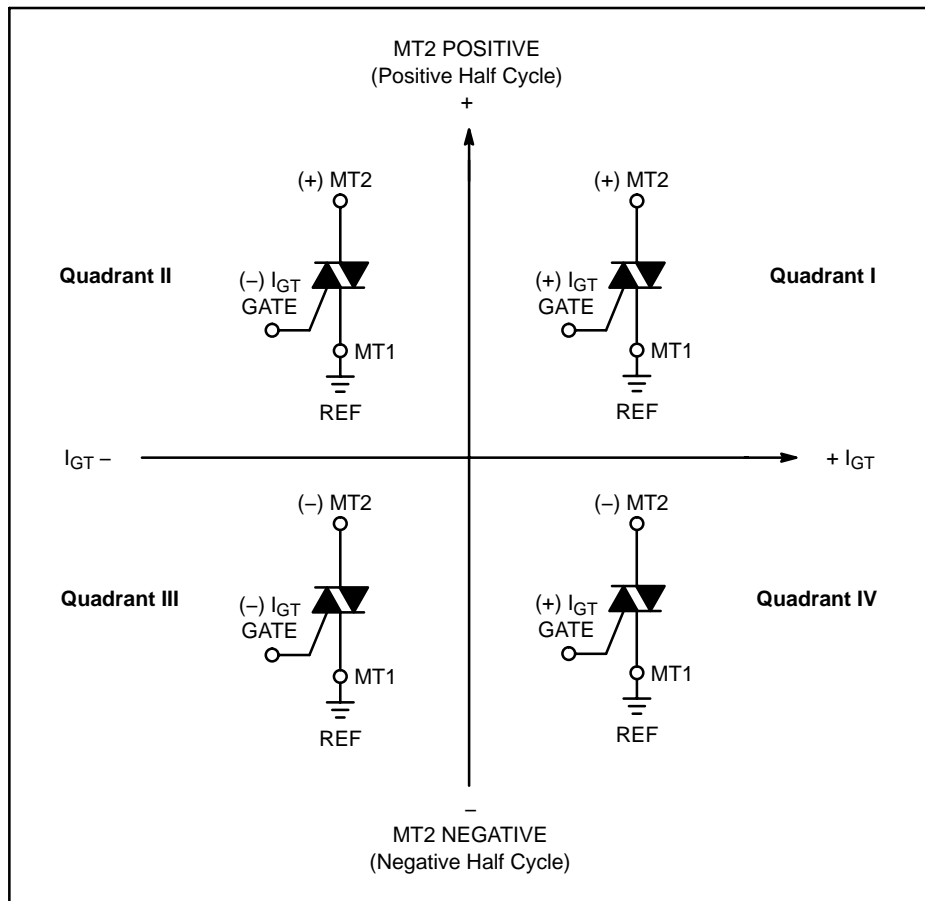
Critical Rate of Rise of Commutation Voltage ( $V_D = \text{Rated } V_{DRM}$ , $I_{TM} = 14 \text{ A}$ , Commutating $di/dt = 5.0 \text{ A/ms}$ , Gate Unenergized, $T_C = 70^{\circ}\text{C}$ )	$dv/dt(c)$	–	5.0	–	$\text{V}/\mu\text{s}$
Critical Rate of Rise of Off-State Voltage ( $V_D = \text{Rated } V_{DRM}$ , Exponential Voltage Rise, Gate Open, $T_C = +70^{\circ}\text{C}$ )	$dv/dt$	–	100	–	$\text{V}/\mu\text{s}$

**Voltage Current Characteristic of Triacs  
(Bidirectional Device)**

Symbol	Parameter
$V_{DRM}$	Peak Repetitive Forward Off State Voltage
$I_{DRM}$	Peak Forward Blocking Current
$V_{RRM}$	Peak Repetitive Reverse Off State Voltage
$I_{RRM}$	Peak Reverse Blocking Current
$V_{TM}$	Maximum On State Voltage
$I_H$	Holding Current



**Quadrant Definitions for a Triac**



All polarities are referenced to MT1.  
 With in-phase signals (using standard AC lines) quadrants I and III are used.

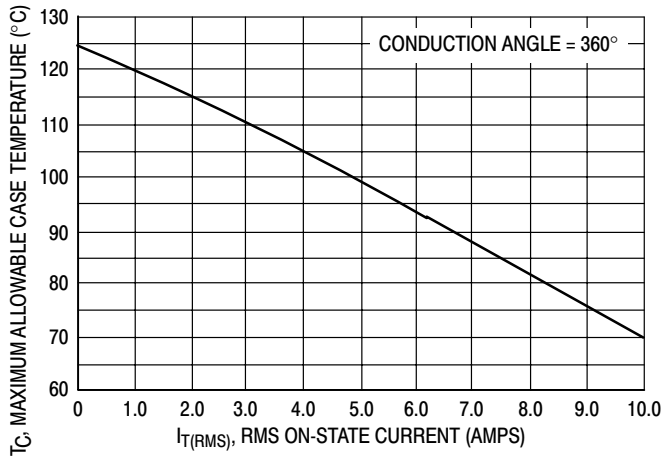


Figure 1. Current Derating

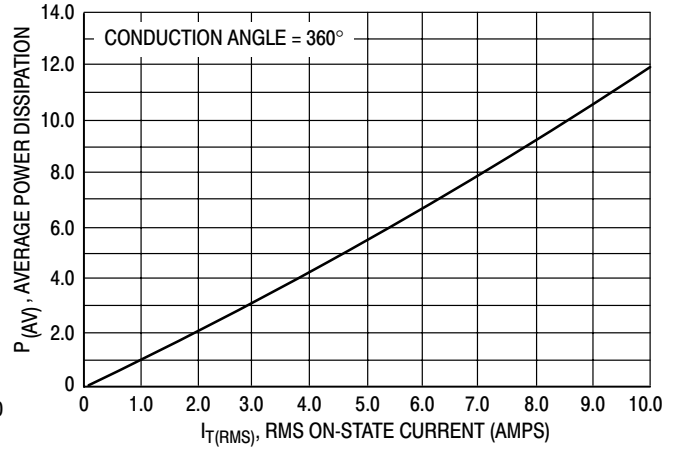


Figure 2. Power Dissipation

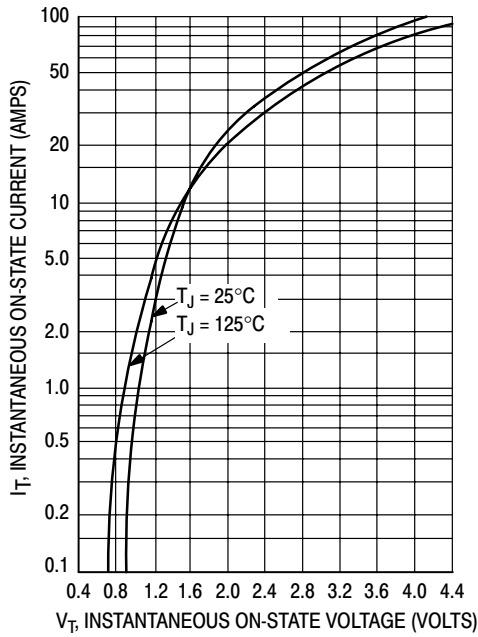


Figure 3. Maximum On-State Characteristics

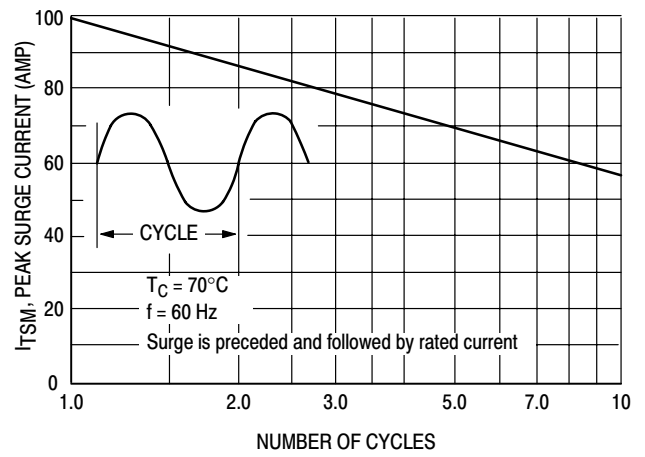


Figure 4. Maximum Non-Repetitive Surge Current

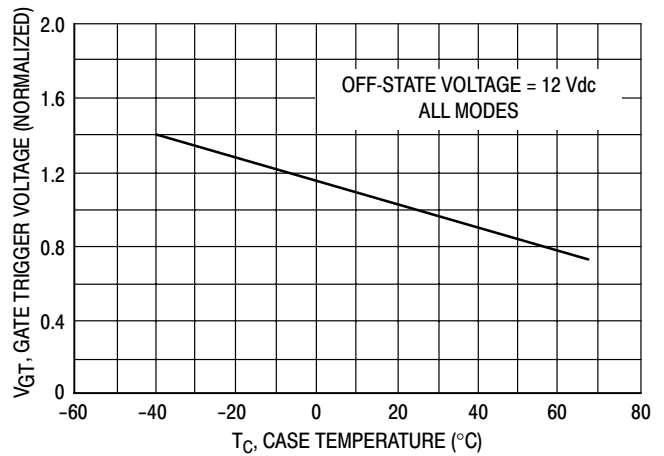


Figure 5. Typical Gate Trigger Voltage

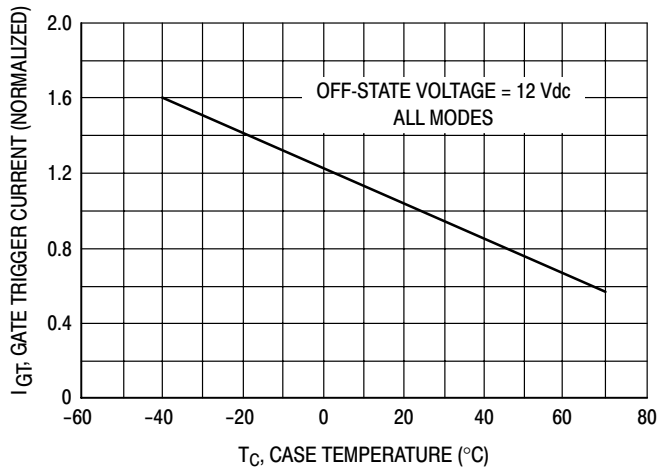


Figure 6. Typical Gate Trigger Current

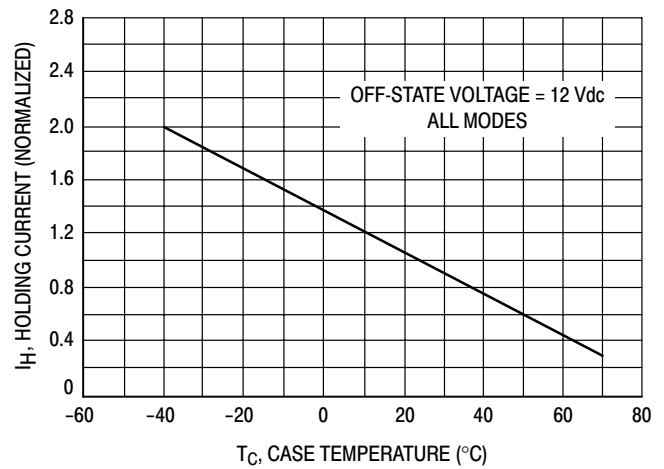


Figure 7. Typical Holding Current

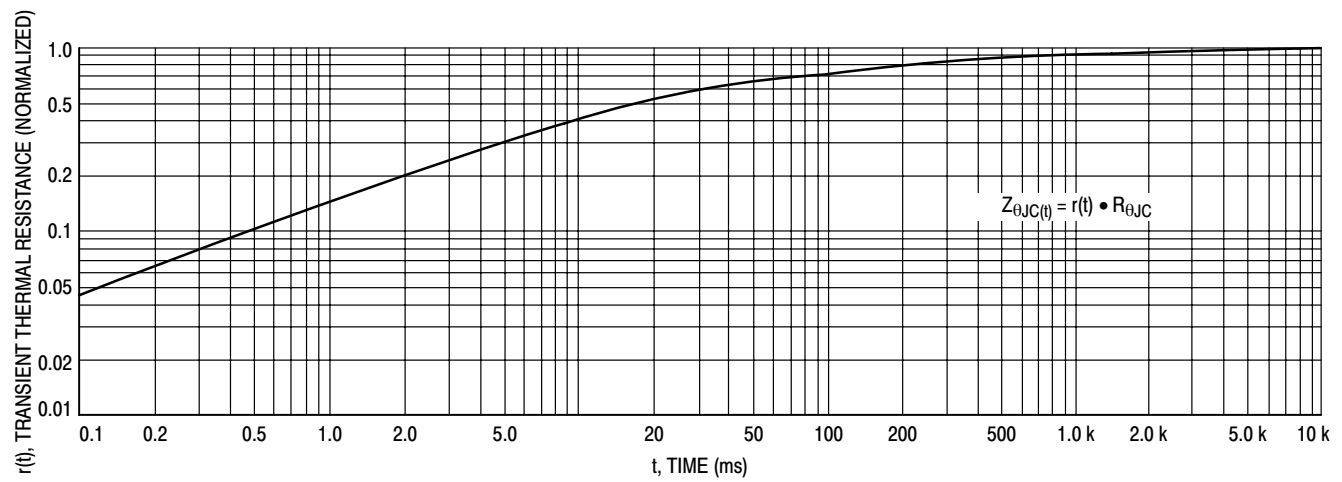
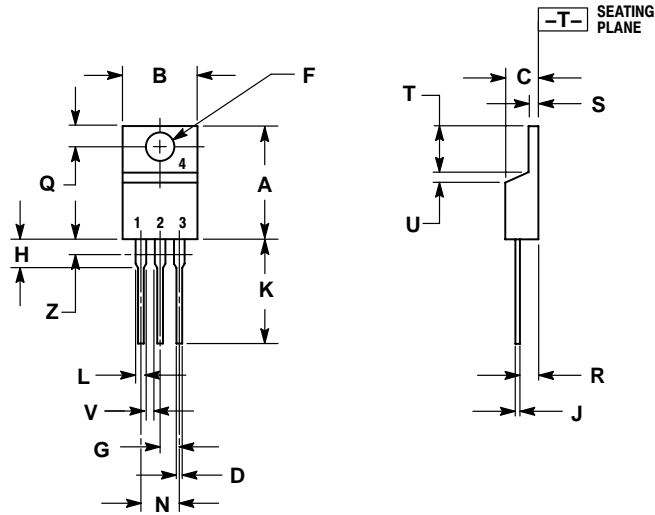


Figure 8. Thermal Response

# MAC3030-8

## PACKAGE DIMENSIONS

TO-220AB  
CASE 221A-07  
ISSUE AA




### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

### STYLE 4:

- PIN 1. MAIN TERMINAL 1
- 2. MAIN TERMINAL 2
- 3. GATE
- 4. MAIN TERMINAL 2

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